

PRODUCT AND SPECIFICATION

LineMaster Fusion

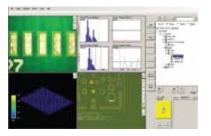
DUAL MODE 3D SPI/AOI



LineMaster Fusion is a revolutionary platform combining the best of ASC International's 3D SPI sensor technology with its sophisticated image and algorithm based AOI sensor technology into a dual purpose, single source solution.

Providing the most accurate and reliable inspection results along with fully automated routines for both 100% coverage or selective inspection makes the **LineMaster Fusion** an exceptional value for the electronics manufacturer searching for a tool to significantly improve both quality and productivity.

LineMaster Fusion Overview

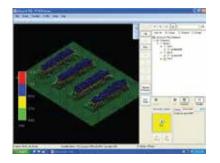


Fully Automated SPi

Simple to use 5 minute Gerber import programming allows for 100% coverage or selective critical site inspections. Quad mode interface, real-time onboard SPC and many more valuable features positions the LineMaster Fusion top in its class.

True 3D Profile Analysis

User defined color legend coded 3D profiling along with photo realistic imaging. Providing the added benefit of a more comprehensive qualitative analysis strategy to enact the most effective corrective actions.



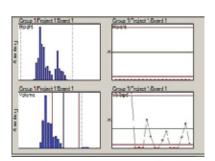
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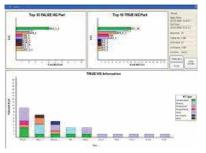
Value Packed AOi

User friendly programming using CPL data. Image and algorithm based inspection principles. Optimized learning mode for minimal flase calls. First Article inspection and general inspection modes for various application requirements.

Onboard SPC and Rework Software Advantage

Fully integrated SPC functionality with X and Moving Range, X-Bar and Sigma, X-Bar and Range, Histogram with Cp and Cpk values for SPI process control. AOI attritube data collection including full traceability through an extensive defect image library and complete defect review list that can be sorted based upon Top 10 defects. An optional remote rework review station can be added to speed up the work flow.





MECHANICAL SPECIFICATIONS

LineMaster Fusion

SPI Features & Specification

Features

- True Height, Area, Volume, X-Y, Registration and Bridging
- Gerber Programming in Less than 5 minutes
- Best in Class Gage R&R (Less than 10%)
- Color Zone Defined and Photo Realistic 3D Profiles
- Onboard SPC with Customized Reports in .csv Format

Sensor Specification

Measurement Principle
Camera Type
Z Resolution:
Lateral Resolution
Measurement Range
Illumination

Phase Shift Interferometry
High Resolution Color CCD
.48um (.019 mils)
6.8 um (.27 mils)
488 um (19,2 mils)
LED Based White Light

AOI Features & Specification

Features

- Absence/Presence, Polarity, OCV, Solder with Bridging, etc.
- Easy to Program using Component Placement Library/CAD
- Intuitive Program Optimization for Low False Calls
- Customized SPC Reports
- Offline Programming and Rework Station Optional

Sensor Specification

Camera Type High Resolution Color CCD Image Resolution 12um, 15 um, 18um
Analysis Method Image and Algorithm Based Illumination LED Based Multi Color Light

General Specification

Operating System Windows 7 Pro Max Board Size 455 mm x 355 r

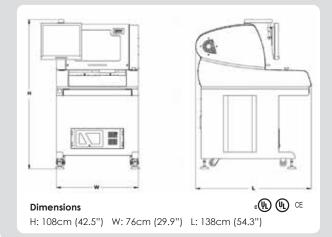
 Max Board Size
 455 mm x 355 mm (18" x 14")

 Optional
 660mm x 558 mm (26" x 22")

 Safety Feature
 Light Curtain Guard

 100.040 VAC 50 (04% 0.4 mm)

Power 100-240 VAC, 50-60 Hz, 2 Amps





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